

Major Ratings and Characteristics

$I_{F(MV)}$	2.5A
V_{RRM}	1000V
I_{FSM}	50A
I_R	5uA
V_F	1.1V
T_{jMAX}	150°C

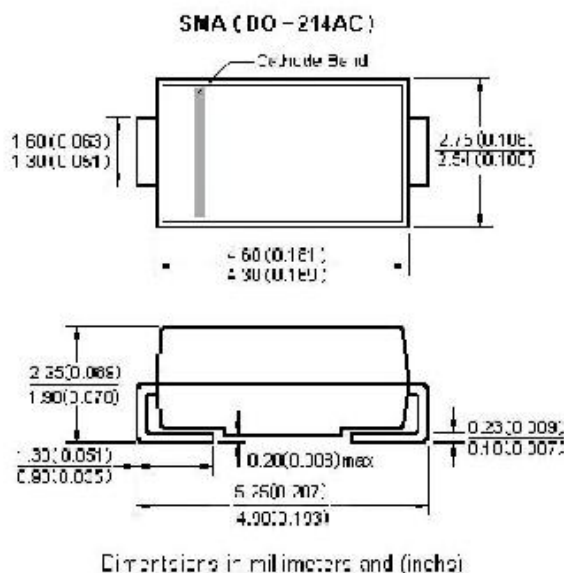


Features

- Low profile space
- Ideal for automated placement
- Glass passivated chip junction
- Low forward voltage drop
- Low leakage current
- High forward surge capability
- High temperature soldering:
260°C/10 seconds at terminals
- Component in accordance to
RoHS 2002/95/1 and WEEE 2002/96/EC

Mechanical Data

- Case: JEDEC DO-214AC molded plastic over glass passivated chip
- Terminals: Solder plated, solderable per J-STD-002B and JESD22-B102D
- Polarity: Laser band denotes cathode end



Maximum Ratings & Thermal Characteristics & Electrical Characteristics

(TA = 25 °C unless otherwise noted)

Type Number	SYMBOL	S3M	unit
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	1000	V
Maximum RMS Voltage	V_{RMS}	700	V
Maximum DC blocking Voltage	V_{DC}	1000	V
Maximum Average Forward Rectified Current .at TA =55°C	$I_{F(AV)}$	2.5	A
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load (JEDEC method)	I_{FSM}	50.0	A
Maximum Forward Voltage at 1.5A DC	V_F	1.1	V
Maximum DC Reverse Current @TA =25°C At rated DC blocking voltage @TA=100°C	I_R	5.0	μA
		100.0	
Typical Junction Capacitance (Note1)	C_j	30	pF
Typical Thermal Resistance (Note 2)	$R_{(JA)}$	90	°C /W
Storage Temperature	T_{STG}	-55 to +150	°C
Operation Junction Temperature	T_J	-55 to +150	°C



FIG.1-TYPICAL FORWARD CURRENT
DERATING CURVE

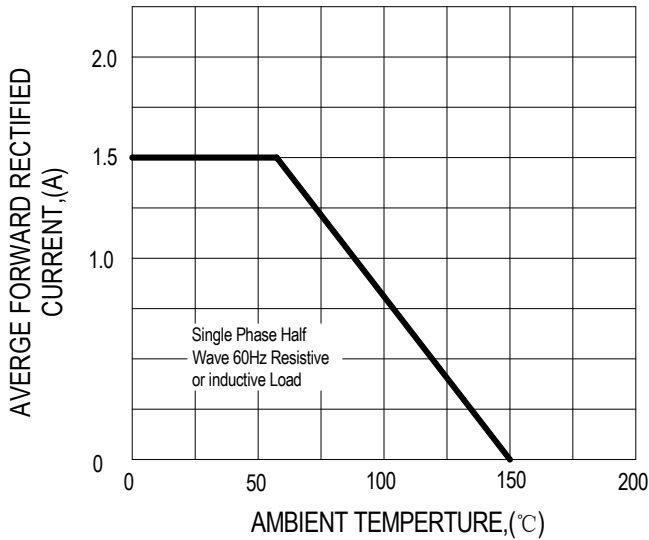


FIG.2-TYPICAL INSTANTANEOUS FORWARD
CHARACTERISTICS

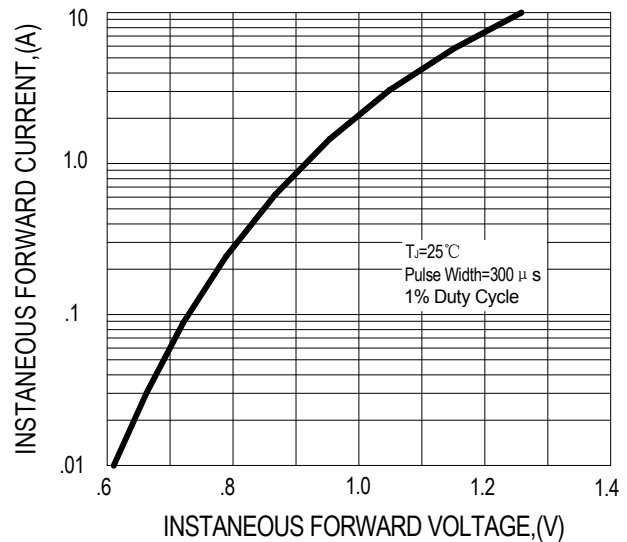


FIG.3-MAXIMUM NON-REPETITIVE FORWARD
SURGE CURRENT

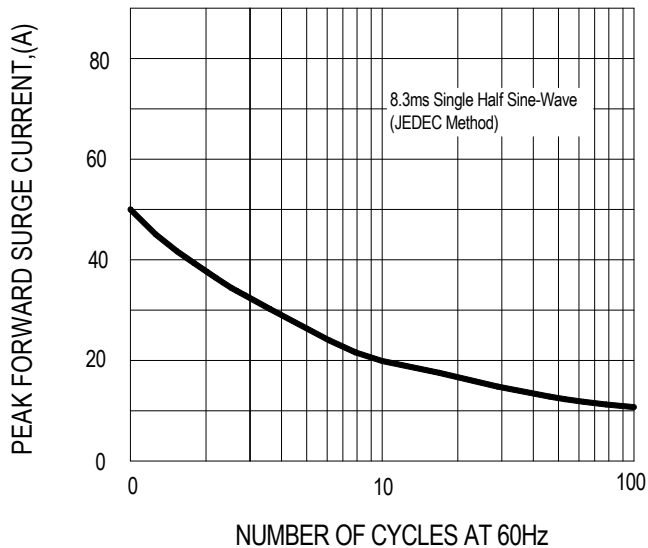


FIG.4-TYPICAL REVERSE CHARACTERISTICS

